$\hfill \square$ MN102L25G , MN102LF25Z , MN102L25Z , MN102L25D , MN102L25A , MN102L25O3 , MN102L62G

Туре	MN102L25G,MN102LF25Z,MN102L25Z,MN102L25D, MN102L25A,MN102L2503,MN102L62G				
ROM (×8-Bit / ×16-Bit)	128 K / 128 K (Flash) / 128 K / 64 K / 32 K / External / 128 K				
RAM (×8-Bit /×16-Bit)	All models : 100 ns (at 4.5 V to 5.5 V, 20 MHz) All models except MN102LF25Z and MN102L62G: 200 ns (at 2.7 V to 3.6 V, 10 MHz) MN102L62G : 148 ns (at 3 0 V to 3.6 V, 13.5MHz) • RESET • Watchdog • Timer Counter 0 to 5 • Timer Counter 6 to 7 • Timer Counter 6 to 7 Compare Capture A • Timer Counter 6 to 7 Compare Capture B • ATC Transfer finish • External 0 to 4 • Serial ch 0, 1 Transmission • Serial ch 0, 1 Reception • NMI Pin • A/D Conversion finish				
Minimum Instruction Execution Time					
Interrupts					
Timer Counter	Timer Counter 0 : 8-Bit × 1 (Timer Output, Event Count) Clock Source 1/1, 1/128 of System Clock, 1/4 of Low Speed Clock, External Clock Interrupt Source Underflow of Timer Counter 0				
	Timer Counter 1 : 8-Bit × 1 (Timer Output, Event Count, A/D Conversion Start up) Clock Source System Clock, 1/4 of Low Speed Clock, External Clock, Timer Counter 0 Output Interrupt Source Underflow of Timer Counter 1				
	Timer Counter 2 to 3 : 8-Bit × 1 (Timer Output, Event Count, UART Baud Rate Generator) Clock Source System Clock, External Clock, Timer Counter 0 Output, Timer Counter 1, 2 Output Underflow of Timer Counter 2, 3				
	Timer Counter 4, 5 : 8-Bit × 1 (Timer Output, Event Count) Clock Source . 1/4 of Low Speed Clock, External Clock, Timer Counter 0 Output, Timer Counter 3, 4 Output Underflow of Timer Counter 4, 5				
	Timer Counter 6, 7 . 16-Bit × 1 (Timer Output, Event Count, Input Capture, Output Compare, PWM Output, 2-Phase Encoder Input) Clock Source System Clock, External Clock, Timer Counter 4, 5 Output Coincidence with Compare Capture A or at Capture, Coincidence with Compare Capture B or at Capture, Underflow of Timer Counter 6, 7				
	Connectable Timer Counter 0 to 5				
Serial Interface	Serial 0:7, 8-Bit × 1 (Common use with UART, Transfer direction of MSB/LSB selectable) Clock Source 1/16 of Timer Counter 2, 1/16 of Timer Counter 3, External Clock, 1/2 of Timer Counter 2				
	Serial 1:7, 8-Bit × 1 (Common use with UART, Transfer direction of MSB/LSB selectable) Clock Source 1/16 of Timer Counter 2, 1/16 of Timer Counter 3, External Clock, 1/2 of Timer Counter 3				
	UART × 2 (Common use with Serial 0, 1)				
	$I^2C \times 2$ (Single master)				
1/0 Pins 1/0 80 48					
A/D Inputs	8-Bit × 8ch (with S/H)				

MN102L25G , MN102L75Z , MN102L25Z , MN102L25D \square MN102L25A , MN102L25O3, MN102L62G

Notes	Burst ROM inferface support, ATC (between serial Och and internal RAM) support
Package	LQFP100-P-1414

Electrical Characteristics

A/D Characteristics (at VDD = 5 V)

Parameter	Symbol	Condition		mis	Limit 199	maa	Unit
A/D Conversion Relative Error		VDD = 5 V, VSS = 0 V	ch0 to 3			±3 +4	LSB
A/D Conversion Time				4 8			μs
Analog Input Voltage	VIA			VSS		DDV	V

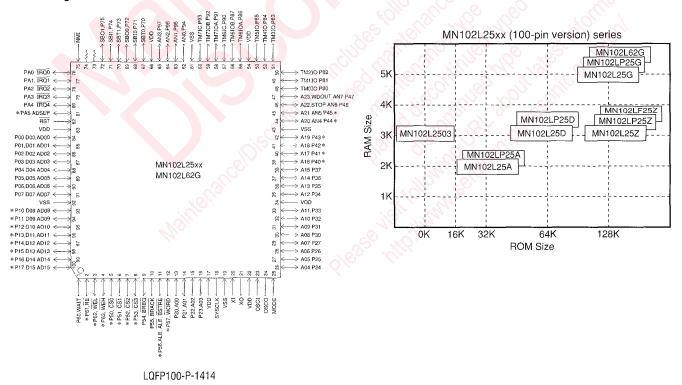
(Ta = 25 °C, VDD = 5.0 V, VSS = 0 V)

A/D Characteristics (at VDD=3V)

Parameter	Symbol	Condition		man	Eismid Typ	max	Unit
A/D Conversion Relative Error	sion Relative Error VDD = 3 V, VSS = 0 V ch0 to 3		±3	LSB			
		0,0	h4 to 7			+4	
A/D Conversion Time				96			μs
Analog Input Voltage	VIA	(0)		VSS		VDD	V

(Ta = 25 °C, VDD = 3.0 V, VSS = 0 V)

Pin Assignment



- * Use of these ports are disabled for MN102L2503
- * The MN102LF25Z is manufactured and sold under license agreement with BULL CP8 Inc Note that MN102LF25Z cannot be used as the IC card

See the next page for support tool.

Support Tool

In-Circuit Emulator	PX-ICE102L00 + PX-PRB102L25				
■ EPROM built-in Type	Туре	MN102LP25G , MN102LP25Z , MN102LP25A [ES (Engineering Sample) available]			
	ROM (× 8-Bit /× 16-Bit)	128 K / 128 K / 32 K			
	RAM (× 8-Bit / × 16-Bit)	5 K / 3 K / 3 K			
	Minimum Instruction Execution Time	100 μs (<mark>at 4 5 V to 5 5 V, 20 MHz)</mark> 2 <mark>00 μs (at 2 7 V to 3.6 V, 10 MHz)</mark>			
	Package	LQFP100-P-1414			

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